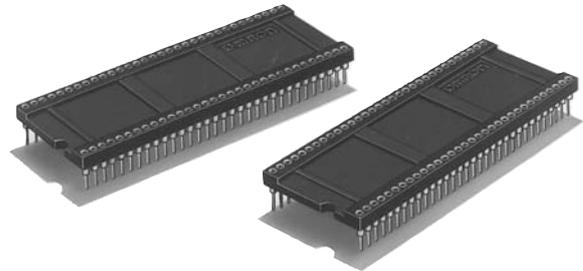


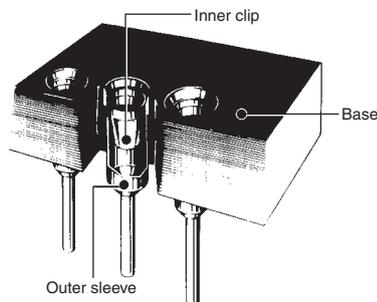
IC Socket for Shrink ICs.

- IC socket designed exclusively for shrink ICs with 1.778-mm contact pitch.
- Round-pin types for long life and good for shock and vibration durability.
- No flux rise.
- See the "Standards certification / conformity list" for information on conformity to certification standards.

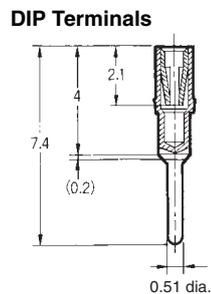


RoHS Compliant

Construction



Contact Dimensions (unit: mm)



Ratings and Characteristics

Rated voltage	1 A
Rated current	150 VAC
Contact resistance	20 mΩ max. (at 20 mV, 100 mA max.)
Insulation resistance	1,000 MΩ min. (at 500 VDC)
Dielectric strength	500 VAC for 1 min (leakage current: 1 mA max.)
Insertion force	3.92 N max. (with test gauge, 0.432 mm dia.)
Removal force	0.64 N min. (with test gauge, 0.432 mm dia.)
Insertion durability	100 times (with 0.75-μm gold plating) 50 times (with 0.25-μm gold plating)
Ambient operating temperature	- 55 to 125°C (with no condensation or icing)

Materials and Finish

Base	PET (UL94 V-0)/black
Inner clips	Beryllium copper/nickel base, 0.75-μm gold plating
Outer sleeves	Brass/nickel base, gold flash plating

Applicable IC Lead Dimensions

Lead	Depth × width (mm)	
Flat leads	0.29 ±0.09 × 0.46 ±0.08 (See note 1.)	
Round leads	0.53 dia. max.	0.41 dia. min.

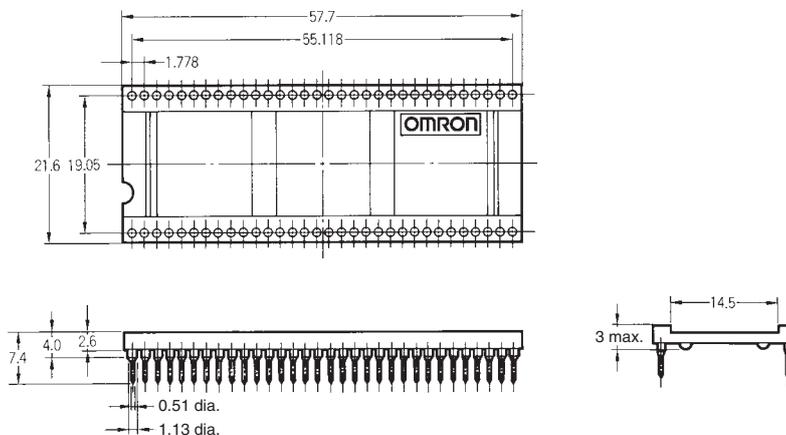
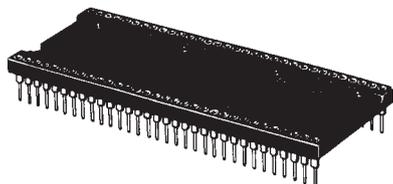
- Note:**
1. Do not use wire where diagonal is more than 0.56 mm.
 2. IC lead length of 3 mm or more (If the lead terminal is too long, the IC may rise up.)

XR3G Shrink IC Sockets

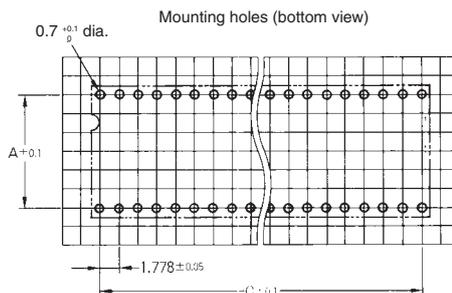
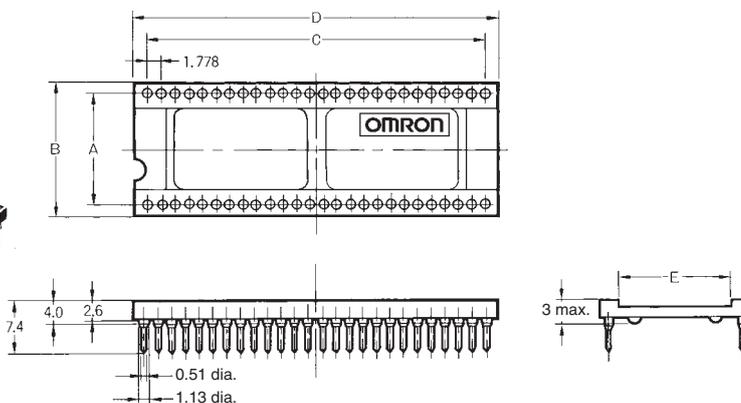
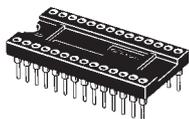
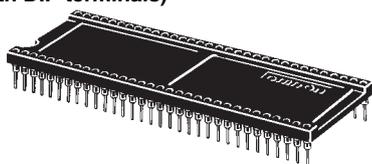
■ Dimensions

(unit: mm)

XR3G-64□1
(With DIP terminals)



XR3G-28□1
XR3G-32□1
XR3G-42□1
XR3G-52□1
(With DIP terminals)



Dimensions

No. of contacts	Dimensions (mm)				
	A	B	C	D	E
28	10.16	12.7	23.114	25.7	5.6
32	10.16	12.7	26.670	29.2	5.6
42	15.24	17.8	35.560	38.1	10.7
52	15.24	17.8	44.450	47.0	10.7
64	19.05	21.6	55.118	57.7	14.5

■ Ordering Information

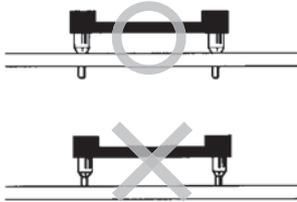
No. of contacts	Sockets with 0.25- μ m gold plating	Sockets with 0.75- μ m gold plating
28	XR3G-2811	XR3G-2801
32	XR3G-3211	XR3G-3201
42	XR3G-4211	XR3G-4201
52	XR3G-5211	XR3G-5201
64	XR3G-6411	XR3G-6401

■ Precautions

Correct Use

Soldering

- When soldering, make sure that the outer sleeve of the IC Socket does not stick out of the circuit board through-holes.



- Make sure that no flux enters the IC Socket from the top.

Automated Soldering Conditions (Jet Flow)

1. Soldering temperature: 250 ±5°C
2. Continuous soldering time: Within 5±1 s

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